

## PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>KIYOSHI SAITO</td><td>08/04/2009</td></tr><tr><td>YUJI UMETANI</td><td>08/05/2009</td></tr><tr><td>HIDEAKI YOSHIMI</td><td>08/05/2009</td></tr></tbody></table>		Name	Execution Date	KIYOSHI SAITO	08/04/2009	YUJI UMETANI	08/05/2009	HIDEAKI YOSHIMI	08/05/2009		
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RECEIVING PARTY DATA											
<table border="1"><tr><td>Name:</td><td>SANYO ELECTRIC CO., LTD</td></tr><tr><td>Street Address:</td><td>5-5, KEIHAN-HONDORI 2-CHOME; MORIGUCHI-SHI</td></tr><tr><td>City:</td><td>MORIGUCHI-SHI, OSAKA</td></tr><tr><td>State/Country:</td><td>JAPAN</td></tr><tr><td>Postal Code:</td><td>570-8677</td></tr></table>		Name:	SANYO ELECTRIC CO., LTD	Street Address:	5-5, KEIHAN-HONDORI 2-CHOME; MORIGUCHI-SHI	City:	MORIGUCHI-SHI, OSAKA	State/Country:	JAPAN	Postal Code:	570-8677
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PROPERTY NUMBERS Total: 1											
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Application Number:	13176118										
CORRESPONDENCE DATA											
Fax Number:	(602)244-3169										
Email:	patents@onsemi.com										
<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>											
Correspondent Name:	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC										
Address Line 1:	5005 EAST MCDOWELL ROAD										
Address Line 2:	A700										
Address Line 4:	PHOENIX, ARIZONA 85008										

PATENT

ATTORNEY DOCKET NUMBER:	200802623
NAME OF SUBMITTER:	KELLY A NELSON
Signature:	/Kelly A. Nelson/
Date:	01/17/2014
Total Attachments: 2 source=200802623_Assignment#page1.tif source=200802623_Assignment#page2.tif	

**MORRISON & FOERSTER LLP**

For good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, the undersigned hereby assigns, transfers and sets over to:

**SANYO Electric Co., Ltd.  
5-5, Keihan-hondori 2-chome  
Moriguchi-shi, Osaka 570-8677 Japan**

**SANYO Semiconductor Co., Ltd.  
1-1-1, Sakata, Oizumi-Machi, Ora-Gun  
Gunma 370-0596 Japan**

(hereinafter designated as the "ASSIGNEES"), its successors and assigns, the entire right, title, and interest for the United States in the invention, and all applications for patent and any Letters Patent which may be granted therefor, including said application, and all United States Letters Patent which may be granted thereof, and all divisions, reissues, continuations and extensions thereof, the said interest being the entire ownership of said Letters Patent when granted to be held by said ASSIGNEES, its successors, assigns or their legal representatives, to the full end of the term for which said Letters Patent may be granted, as fully and entirely as the same would have been and enjoyed by Assignor(s) if this assignment had not been made, the application being known by the title:

**RESIN MOLDED SEMICONDUCTOR DEVICE AND  
MANUFACTURING METHOD THEREOF**

Attorney Docket No.: 606402049000

for which the undersigned has/have executed an application for patent in the United States of America on the same day herewith. Where this instrument is not filed concurrently with the application, the following identifying information may be added after execution:

Serial No.: \_\_\_\_\_ Filing Date: \_\_\_\_\_

1. The undersigned hereby agrees to sign and execute any further documents and instruments which may be necessary, lawful and proper in the prosecution of said above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reexamination or reissue application or in any amendments, extension of interference proceedings, or otherwise to secure the title thereto to the ASSIGNEES.

2. The undersigned agrees to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property of similar agreements.

3. The undersigned agrees to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the ASSIGNEES.

4. The undersigned hereby authorizes and requests the Commissioner of Patents in the United States to issue any and all Letters Patent resulting from said application or any division or divisions or continuing applications thereof to the said ASSIGNEES.

5. The undersigned hereby grants to the firm of Morrison & Foerster LLP the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

IN WITNESS WHEREBY, executed by the undersigned on the date opposite the undersigned name.

Aug. 4. 2009  
Date

Kiyoshi Saito  
Name: Kiyoshi SAITO

Aug. 5. 2009  
Date

Yuji Umetani  
Name: Yuji UMETANI

Aug. 5. 2009  
Date

hideaki yoshimi  
Name: Hideaki YOSHIMI